

ABSTRACT

To provide a mold release film having excellent releasing properties for a sealed body from a mold and excellent followability to a mold requiring significant deformation, in a method for producing a sealed body wherein a structure comprising a substrate, a semiconductor element and connection terminals, is disposed in a mold requiring significant deformation and sealed with a curable resin to form a resin sealed portion having a thickness of at least 3 mm. The mold release film has a first layer to be in contact with the curable resin at the time of forming the resin sealed portion, and a second layer, wherein the first layer has a thickness of from 5 to 30 μm and is made of at least one member selected from the group consisting of a fluororesin and a polyolefin having a melting point of at least 200°C, and the second layer has a thickness of from 38 to 100 μm , a product of the tensile storage modulus (MPa) at 180°C and the thickness (μm) being at most 18,000 (MPa· μm), and a product of the tensile stress at break (MPa) at 180°C and the thickness (μm) being at least 2,000 (MPa· μm).